

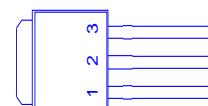
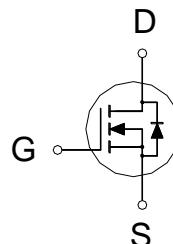
NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****PG1010BIS**

TO-251(IS)

Halogen-Free & Lead-Free

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
100V	10.5mΩ	64A


 1. GATE
 2. DRAIN
 3. SOURCE
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ²	$T_C = 25^\circ C$	I_D	64	A
	$T_C = 100^\circ C$		45	
Pulsed Drain Current ¹		I_{DM}	150	A
Avalanche Current		I_{AS}	12.5	
Avalanche Energy	$L = 1mH$	E_{AS}	78.1	mJ
Power Dissipation	$T_C = 25^\circ C$	P_D	100	W
	$T_C = 100^\circ C$		50	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 175	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		1.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.²Package limitation current is 55A**ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ C$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.4	2	3	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100V, V_{GS} = 0V$			1	μA
		$V_{DS} = 100V, V_{GS} = 0V, T_J = 125^\circ C$			100	

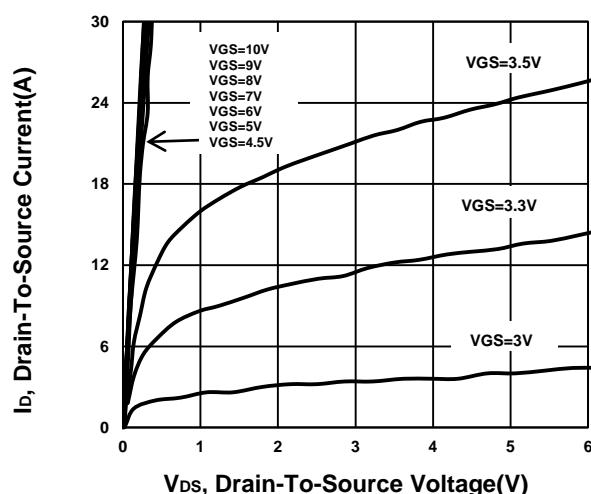
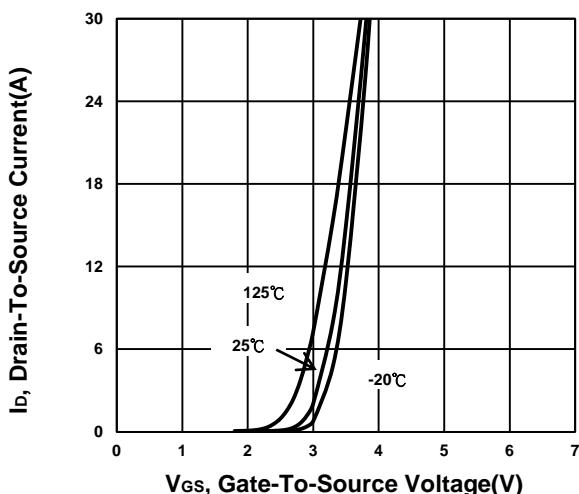
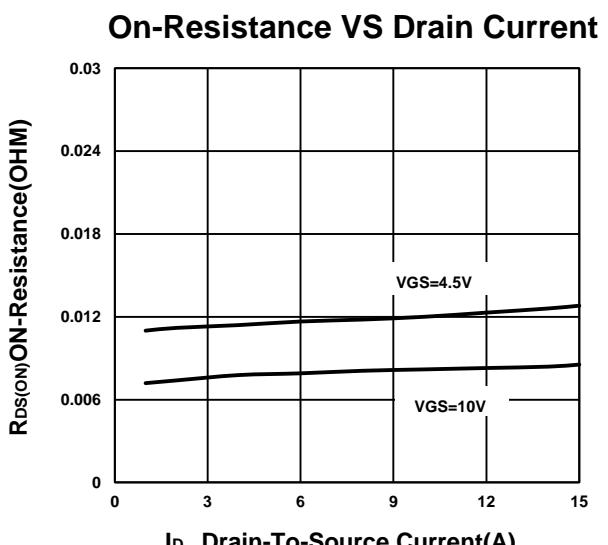
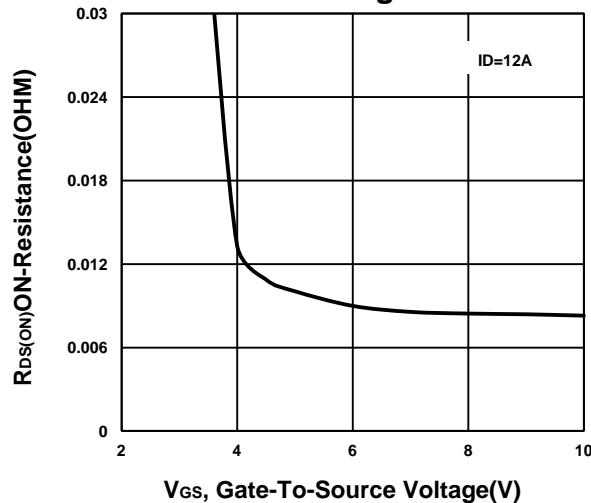
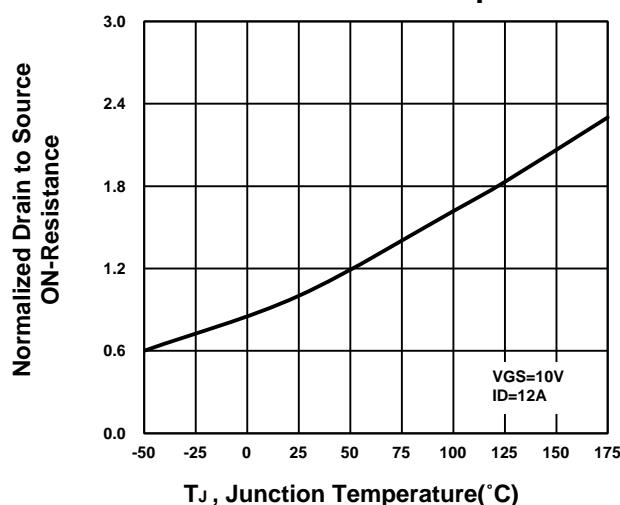
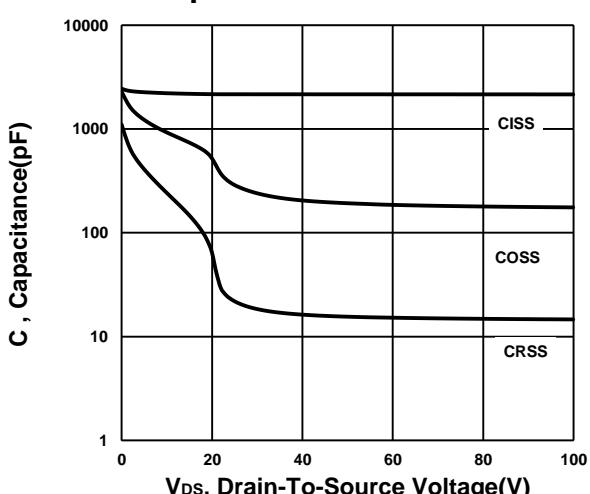
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Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 10A$	12	15	$m\Omega$
		$V_{GS} = 10V, I_D = 12A$	8.3	10.5	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 12A$	60		S
DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 50V, f = 1MHz$	2164		pF
Output Capacitance	C_{oss}		191		
Reverse Transfer Capacitance	C_{rss}		15		
Gate Resistance	R_g		1.6		Ω
Total Gate Charge ²	Q_g	$V_{DS} = 50V, I_D = 12A$	40		nC
Gate-Source Charge ²	Q_{gs}		23		
Gate-Drain Charge ²	Q_{gd}		6.8		
Turn-On Delay Time ²	$t_{d(on)}$		12		
Rise Time ²	t_r	$V_{DD} = 50V,$ $I_D \approx 12A, V_{GS} = 10V, R_{GEN} = 6\Omega$	32		nS
Turn-Off Delay Time ²	$t_{d(off)}$		40		
Fall Time ²	t_f		57		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)					
Continuous Current ³	I_S			64	A
Forward Voltage ¹	V_{SD}	$I_F = 12A, V_{GS} = 0V$		1.2	V
Reverse Recovery Time	t_{rr}	$I_F = 12A, dI_F/dt = 100A/\mu s$	30		nS
Reverse Recovery Charge	Q_{rr}		32		nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Package limitation current is 55A

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Halogen-Free & Lead-Free****Output Characteristics****Transfer Characteristics****On-Resistance VS Gate-to-Source Voltage****On-Resistance VS Temperature****Capacitance Characteristic**

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